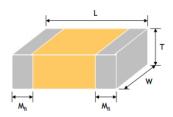
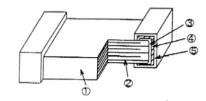
High Q/Low ESR Multilayer Ceramic Chip Capacitors - GHQ Series



■ Construction and Dimensions





Scope

- Used at high frequencies, small temperature coefficient of capacitance, typical within +/-30ppm/C required for NPO (COG) classification.
- Excellent conductivity internal electrode

Features

- High Q and low ESR performance at high frequency.
- Quality improvement of telephone calls for low power loss and better performance.

Applications

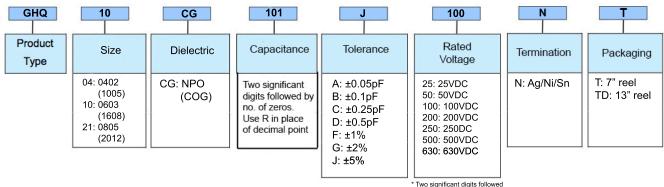
- Mobile telecommunication; mobile phones, WLAN
- RF module: power amplifier, VCO
- Tuners

No.	Na	me	NP0*	NP0
①	Ceramio	material	CaZrO ₃ / Ba	TiO₃ based
2	Inner e	lectrode	AgPd alloy	Ni
3		Inner layer	Ag	Cu
4	Termination	Middle layer	N	i
(5)		Outer layer	Si	n

^{*} Partial NP0 items are with Ag/Ni/Sn(NME) terminations, please ref to product range for detail.

Size Inch(mm)	L (mm)	W (mm)	T (mm)	Remark	M _a (mm)
0402 (1005)	1.00±0.05	0.50±0.05	0.50±0.05	#	0.25 +0.05/-0.10
0603 (1608)	1.60±0.10	0.8±0.10	0.80±0.07		0.40.0.45
	1.60 +0.15/-0.10	0.80 +0.15/-0.10	0.80 +0.15/-0.10		0.40±0.15
			0.60±0.10		
0805 (2012)	2.00±0.15	1.25±0.10	0.80±0.10		0.50±0.20
5.47			1.25±0.10	#	

#Reflow soldering only is recommended



* Two significant digits followed by no. of zeros. And R is in place of decimal point.



■ Capacitance Range

DIMENSI	ON (MM)	G	HQ0	4	1	GH	Q10				GH	Q21		
L(I	L1)	1	.00±0.0)5	1.60	±1.0	1.60+0.	15/-0.10	2.00±0.15					
	w		.50±0.0		0.80±0.10 0.80+0.15			1.25±0.10						
BW(L	.2/L3)	0.25	+0.05/-	0.10		0.40:	±0.15		0.50±0.20					
	ectric		COG				OG		COG					
H (r	max)		0.55		0.8		0.95			0.9			1.35	
L	Voltage	16	25	50	16	25	50	100	50	100	200	250	500	630
	Range	10		-						100		200	300	
0.5pF	OR5										 			
0.6	OR6													
0.7	OR7													, ,
0.8	OR8													
0.9	OR9													
1.2	1R0 1R2													
1.5	1R5													
1.8	1R8				-									
2.2	2R2													
2.7	2R7													
3.3	3R3													
3.9	3R9													
4.7 5.6	4R7 5R6													
6.8	6R8		-		4									
8.2	8R2				-									
10pF	100													
12	120				9									
15	150													7
18	180													
22 27	220 270													
33	330													
39	390					.c								
47	470													
56	560													
68	680		-											
82 100	820 101													
120	121													
150	151													
180	181													
220	221													
270	271								_					
330 390	331 391								_					
470	471								\vdash	_				
560	561													7
680	681			1										
820	821	- 7	1											-
1000	102													
1200	122		1									_		
1500 1800	152 182	-	1	-										1
2200	222		 						\vdash	<u> </u>				
2700	272		1											,
3300	332		<u> </u>											1

^{1. 0402,} Capacitance <0.5pF; on request

^{2.} For more information about products with special capacitance or other data, please contact your Cal-Chip Sales Representative.



General Electrical Data

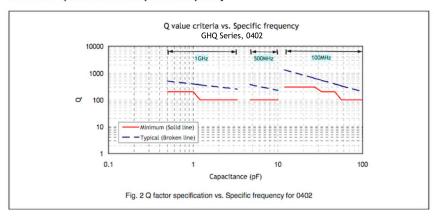
Dielectric	NP0				
Size	0402, 0603, 0805				
	0402: 0.5pF to 470pF**				
Capacitance*	0603: 0.5pF to 3300pF				
	0805: 0.5pF to 390pF				
	Cap≤5pF ^{#1} : A (±0.05pF), B (±0.1pF), C (±0.25pF)				
Capacitance tolerance	5pF <cap<10pf: (±0.25pf),="" (±0.5pf)<="" c="" d="" td=""></cap<10pf:>				
	Cap≥10pF: F (±1%), G (±2%), J (±5%)				
Rated voltage (WVDC)	16V, 25V, 50V, 100V, 200V, 250V, 500V, 630V				
a.	Cap<30pF: Q≥400+20C				
Q*	Cap≥30pF: Q≥1000				
Insulation resistance at Ur	≥10GΩ or RxC≥100Ω-F whichever is smaller.				
Operating temperature	-55 to +125°C				
Capacitance change	±30ppm				
Termination	Ni/Sn (lead-free termination)				

^{#1:} NP0, 0.1pF product only provide B tolerance

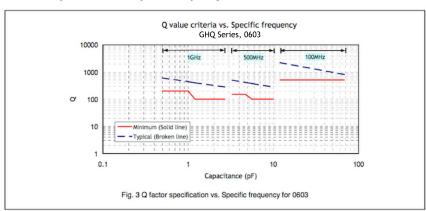
Apply 1.0±0.2Vrms, 1.0MHz±10% for Cap≤1000pF and 1.0±0.2Vrms, 1.0kHz±10% for Cap>1000pF.

Electrical Characteristics

■ Q factor specification vs. Specific frequency



■ Q factor specification vs. Specific frequency



Calchip Electronics, INC. Phone: (215) 942-8900

www.calchipelectronics.com Fax : (215) 942-6400

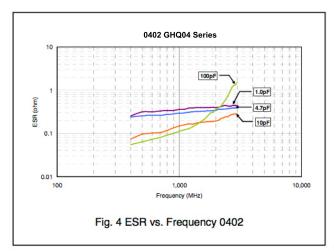
^{*} Measured at the conditions of 25°C ambient temperature and 30~70% related humidity.

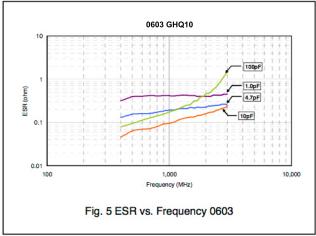
^{** 0402,} Capacitance <0.5pF: On request.



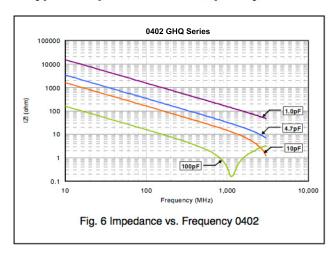
■ General Electrical Data

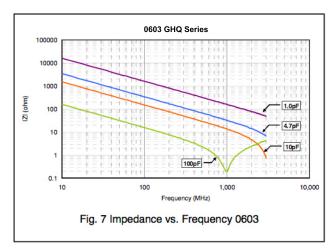
■ Typical ESR vs. Frequency



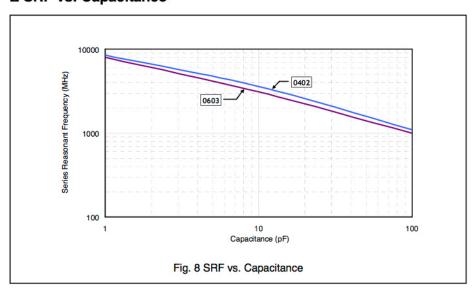


■ Typical Impedance vs. Frequency





SRF vs. Capacitance





■ Reliability Test Conditions and Requirements

No.	Item	Test Conditions	Requirements
1.	Visual and		* No remarkable defect.
	Mechanical		* Dimensions to conform to individual specification sheet.
2.	Capacitance	Cap≤1000pF, 1.0±0.2Vrms, 1MHz±10%	* Shall not exceed the limits given in the detailed spec.
3.	Q/ D.F.	Cap>1000pF, 1.0±0.2Vrms, 1KHz±10%	* NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C
	(Dissipation	At 25°C ambient temperature.	
	Factor)		
4.	Dielectric	* To apply voltage: (≤100V) 250% of rated voltage.	* No evidence of damage or flash over during test.
	Strength	* Duration: 1 to 5 sec.	
		* Charge and discharge current less than 50mA.	
		* To apply voltage:	
		200V~300V ≥2 times VDC	
		500V~999V ≥1.5 times VDC	
		* Cut-off, set at 10mA	
		* TEST= 15 sec.	
		* RAMP=0	
5.	Insulation	Rated voltage:<200V	≥10GΩ
	Resistance	To apply rated voltage for max. 120 sec.	
		Rated voltage:200~630V	≥10GΩ or RxC≥100Ω-F whichever is smaller
		To apply rated voltage (500V max.) for 60 sec.	
6.	Temperature	With no electrical load.	* Capacitance change: within ±30ppm/°C
	Coefficient	Operating temperature: -55~125°C at 25°C	
7.	Adhesive	* Pressurizing force :	* No remarkable damage or removal of the terminations.
	Strength of	5N (≤0603) and 10N (>0603)	
	Termination	* Test time: 10±1 sec.	
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.
	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.
	*	* Test time: 6 hrs. (Two hrs each in three mutually	
		perpendicular directions.)	
		* Measurement to be made after keeping at room temp. for	
		24±2 hrs.	
9.	Solderability	* Solder temperature: 235±5°C	95% min. coverage of all metalized area.
		* Dipping time: 2±0.5 sec.	
10.	Bending Test	* The middle part of substrate shall be pressurized by means	* No remarkable damage.
	2377	of the pressurizing rod at a rate of about 1 mm per second until	* Cap change: within ±5.0% or ±0.5pF whichever is larger.
		the deflection becomes 1 mm and then the pressure shall be	(This capacitance change means the change of capacitance under
		maintained for 5±1 sec.	specified flexure of substrate from the capacitance measured before
		* Measurement to be made after keeping at room temp. for	the test.)
		24±2 hrs.	
11.	Resistance to	* Solder temperature: 260±5°C	* No remarkable damage.
	Soldering Heat	* Dipping time: 10±1 sec	* Cap change: within ±2.5% or ±0.25pF whichever is larger.
		* Preheating: 120 to 150°C for 1 minute before immerse the	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.
		capacitor in a eutectic solder.	* 25% max. leaching on each edge.
		* Before initial measurement (Class II only): Perform	
		150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp.	
		* Measurement to be made after keeping at room temp. for	
		24±2 hrs.	

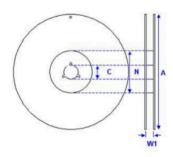
Calchip Electronics, INC. Phone: (215) 942-8900

www.calchipelectronics.com Fax : (215) 942-6400



No.	Item	Test Condition			Requirements			
12.	Temperature Cycle	time. Step 1 2 3 4 * Before i 150+0/-10 * Measure	Temp. (°C) Min. operating temp. +0/-3 Room temp. Max. operating temp. +3/-0 Room temp. nitial measurement (Class II or 0°C for 1 hr and then set for 24 ement to be made after keeping.	Time (min.) 30±3 2~3 30±3 2~3 aly): Perform ±2 hrs at room temp	* No remarkable damage. * Cap change : within ±2.5% or ±0.25pF whichever is larger. * Q/D.F., I.R. and dielectric strength: To meet initial requirements.			
13.	Humidity (Damp Heat) Steady State	24±2 hrs. * Test temp.: 40±2°C * Humidity: 90~95% RH * Test time: 500+24/-0hrs. *Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp. * Measurement to be made after keeping at room temp. for			* No remarkable damage. * Cap change: within ±5.0% or ±0.5pF whichever is larger. * Q/D.F. value: NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C Cap<10pF; Q≥200+10C * I.R.: ≥1GΩor RxC≥50Ω-F whichever is smaller.			
14.	Humidity (Damp Heat) Load	* Humidity * Test tim * To apply * Before i	np.: 40±2°C y: 90~95%RH e: 500+24/-0 hrs. v voltage: rated voltage (Max. nitial measurement (Class II or or 1hr at 40°C and then set for 2 ement to be made after keepings	nly): To apply test 24±2 hrs at room ter	* No remarkable damage. * Cap change: within ±7.5% or ±0.75pF whichever is larger. * Q/D.F. value: NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C * I.R.: ≥500MΩ or RxC≥25Ω-F whichever is smaller. p.			
15.	High Temperature Load (Endurance)	* Test tern NP0: 12 * To apply (1) <500V (2) 500V: (3) ≥630V * Test tim *Before ir voltage for	np.:	t for 24±2 hrs at roo	* No remarkable damage. * Cap change: within ±3.0% or ±0.3pF whichever is larger. * Q/D.F. value: NP0: Cap≥30pF, Q≥350 10pF≤Cap<30pF, Q≥275+2.5C Cap<10pF, Q≥200+10C * I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.			

■ Packaging



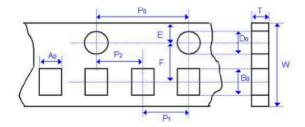
Size	Thickness	Thickness Paper Tap		Plastic Tape		
Size	(mm)	7" reel	13" reel	7" reel	13" reel	
0402	0.50±0.05	10K	50K			
0603	0.80±0.07	4K	15K			
0003	0.80 +0.15/-0.10	4K	15K			
	0.60±0.10	4K	15K			
0805	0.80±0.10	410	15K			
	1.25±0.10			3K	10K	



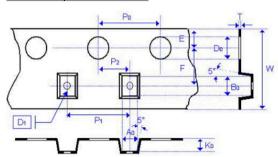
Tape and Reel Dimensions

Size	0402, 0603, 0805					
Reel size	7"	10"	13"			
С	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2			
W ₁	8.4+1.5/-0	8.4+1.5/-0	8.4+1.5/-0			
Α	178.0±0.10	250.0±1.0	330.0±1.0			
N	60.0+1.0/-0	100.0±1.0	100±1.0			

Paper Tape Dimensions



Plastic Tape Dimensions



Size	0402	0603	Α	0805	
Thickness	N	S, X	Α	В	C, D, I
A ₀	0.62±0.05	1.02±0.05	1.50±0.10	1.50±0.10	<1.57
B ₀	1.12±0.05	1.80±0.05	2.30±0.10	2.30±0.10	<2.40
T	0.60±0.05	0.95±0.05	0.75±0.05	0.95±0.05	0.23±0.05
K ₀	<u>;</u>	-	-	-	<2.50
w	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10	8.00±0.10
P ₀	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
10xP₀	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10	40.0±0.10
P ₁	2.00±0.05	4.00±0.10	4.00±0.10	4.00±0.10	4.00±0.10
P ₂	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05	2.00±0.05
D ₀	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.50±0.05
D ₁	-	-	-	- 9	1.00±0.10
E	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.05	1.75±0.10
F	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05	3.50±0.05

■ Storage and Handling Conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability.
 Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Calchip Electronics, INC. Phone: (215) 942-8900



■ Recommended Soldering Conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.

